AMENDMENTS TO THE SPECIFICATION:

On page 10, replace paragraph **[0056]** with the following paragraph:

[0056] It has been found in experiments that cracks of the solder layer 146 or the FETs 66 (i.e., the semiconductor chips) and peeling of the FETs 66 from the solder layer 146 are effectively prevented without the conventional heat spreaders if the synthetic resin 80 at least meets the following condition. Preferably, the synthetic resin 80 is epoxide that has a coefficient of linear expansion generally less than 23 ppm/°K. The resin under this condition effectively relieves the thermal stress affected to the solder layer 146. Other synthetic resins may be used instead of the epoxide, but the resin should have a coefficient of linear expansion less than the coefficient of linear expansion of the lands 144 or the coefficient of linear expansion of the ~~semiconductor chip (i.e., the FET 66)~~ substrate 72 in order to produce the beneficial effect described above. In other words, the coefficient of linear expansion of the resin is generally less than one of the coefficient of linear expansion of the substrate 72 and the coefficient of linear expansion of the lands 144, and the coefficient of linear expansion of the resin is generally greater than the other one of the coefficient of linear expansion of the substrate 72 and the coefficient of linear expansion of the lands 144. Adjustment of the proportions of the components of the synthetic resin can produce the desired coefficient of linear expansion. No side walls are necessary if the epoxide is applied because the epoxide has sufficient viscosity. Materials other than aluminum or copper can be used for the substrate or the lands inasmuch as the foregoing condition is met.

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